

Technical Data Sheet

PI Polyimide Tecasint® 1011 natural

Polyimide (PI), unfilled

Typical Properties

- High thermal and mechanical load capacity
- Very good thermal stability
- Good chemical resistance
- Very good electrical insulation
- Resistance against high-energy radiation
- Low outgassing (ECSS-Q-70-02)
- High creep resistance
- Sensitive to hydrolysis at elevated temperatures

Typical Industries

- Mechanical engineering
- Precision engineering
- Aircraft and aerospace technology
- Cryogenic engineering
- Electronics
- Electrical engineering
- Nuclear and vacuum technology
- Semiconductor technology

	Test Method	Unit	Value
General Properties			
Chemical Designation			PI (Polyimide)
Colour			black
Density		g / cm ³	1.34
Water absorption (24 h in water, 23 °C)	DIN EN ISO 62	%	1.3
Water absorption (24 h in water, 80 °C)	DIN EN ISO 62	%	3.8
Outgassing in high vacuum	ECSS-Q-70-02		passed
Flammability	DIN IEC 60695-11-10	UL94	V0
Mechanical Properties			
Tensile strength (50 mm/min)	DIN EN ISO 527-1	MPa	116
Modulus of elasticity, tensile (1 mm/min)	DIN EN ISO 527-1	MPa	3600
Elongation at break (50 mm/min)	DIN EN ISO 527-1	%	3.8
Flexural strength (10 mm/min)	DIN EN ISO 178	MPa	170
Modulus of elasticity, flexural (2 mm/min)	DIN EN ISO 178	MPa	3450
Compressive strength (10 mm/min)	EN ISO 604	MPa	450
Compressive strength at 10% strain (10 mm/min)	EN ISO 604	MPa	190
Compression modulus (1 mm/min)	EN ISO 604	MPa	3647
Compressive strain at break (10 mm/min)	EN ISO 604	%	45

	Test Method	Unit	Value
Impact strength, Charpy (max. 7.5 J)	DIN EN ISO 179-1	kJ / m	75.8
Notched impact strength, Charpy (max. 7.5 J)	DIN EN ISO 179-1	kJ / m	5
Shore hardness	DIN EN ISO 868	Shore D	90
Thermal Properties			
Glass transition temperature	DMA	°C	383
Heat distortion temperature (1.85 MPa)	DIN 53 461	°C	368
Thermal expansion, CLTE (50–200 °C)	DIN 53752	10 ⁻⁵ K ⁻¹	4.3 / 4.3
Thermal expansion, CLTE (200–300 °C)	DIN 53752	10 ⁻⁵ K ⁻¹	5.3 / 5.3
Specific heat		J / (g * K)	1.04
Thermal conductivity (40 °C)	ISO 8302	W / (K * m)	0.22
Electrical Properties			
Surface resistivity (23 °C)	DIN IEC 60093	Ω	>10 ¹⁵
Volume resistivity (23 °C)	DIN IEC 60093	Ω * cm	>10 ¹⁵
Electric strength DC (23 °C)	ISO 60243-1	kV / mm	>35
Dielectric dissipation factor (50 Hz)	DIN 53483-1		2.2 · 10 ⁻²
Dielectric dissipation factor (1 kHz)	DIN 53483-1		2.5 · 10 ⁻²
Dielectric dissipation factor (1 MHz)	DIN 53483-1		1.5 · 10 ⁻³
Dielectric constant (50 Hz)	DIN 53483-1		3.8
Dielectric constant (1 kHz)	DIN 53483-1		3.9
Dielectric constant (1 MHz)	DIN 53483-1		3.7

PI Polyimide Terasint 1011 natural shows significant water uptake. If parts are to undergo rapid heating above 200 °C, they must be pre-dried (drying process: 2 hours per 3 mm wall thickness at 150 °C). The values stated are guideline values for material selection and are not guaranteed minimum or maximum values in the sense of a specification. Since the properties also depend on the dimensions and orientation of the semi-finished product, application-specific individual testing is required; responsibility for suitability in the specific application lies with the customer. The product is not intended for medical or dental implants.